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General Description

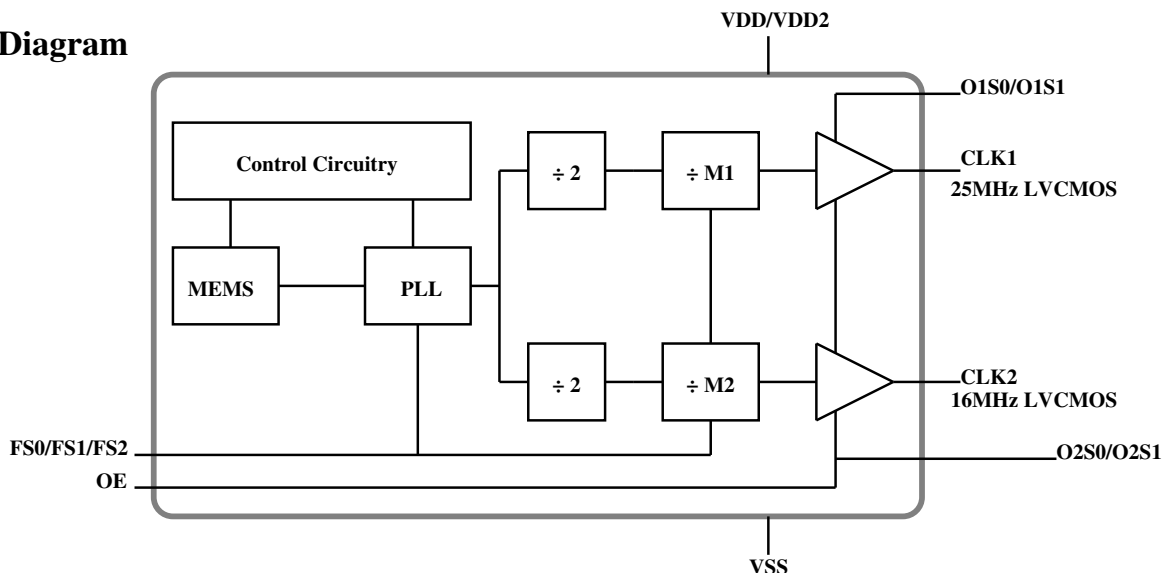
The DSC2011FI2-F0035 is a programmable, high performance dual LVCMOS output oscillator utilizing Microchip's proven silicon MEMS technology to provide excellent jitter and stability while incorporating additional device functionality. Two LVCMOS outputs are controlled by separate supply voltages to allow for independent voltage level control. The frequencies of the outputs can be identical or independently derived from a common PLL frequency source.

The DSC2011FI2-F0035 has provision for up to eight user-defined pre-programmed, pin-selectable output frequency combinations. The DSC2011FI2-F0035 is also equipped with independent pin-selectable output drive strengths to reduce EMI and noise.

Applications

- Consumer Electronics
- Storage Area Networks
 - SATA, SAS, Fibre Channel
- Passive Optical Networks
 - EPON, 10G-EPON, GPON, 10G-GPON
- Ethernet
 - 1G, 10GBASE-T/KR/LR/SR, and FCoE
- HD/SD/SDI Video & Surveillance
- PCI Express
- Automotive

Block Diagram



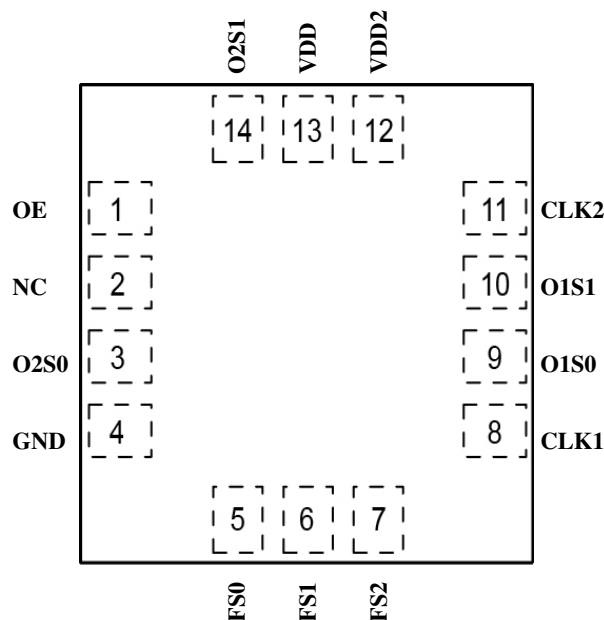
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Ordering Information

Ordering Part Number	Industrial Temperature Range	Shipping	Package
DSC2011FI2-F0035	-40°C to +85°C	Tube	14-pin 3.2mm x 2.5mm QFN
DSC2011FI2-F0035T	-40°C to +85°C	Tape and Reel	14-pin 3.2mm x 2.5mm QFN

Devices are Green and RoHS compliant. Sample material may have only a partial top mark.

Pin Configuration



14-pin 3.2mm x 2.5mm QFN

Pin Description

Pin Number	Pin Name	Pin Type	Pin Function
1	OE	I	Enables outputs when high and disables outputs when low
2	NC		Leave unconnected or connect to ground
3	O2S0	I	Least significant bit for drive strength selection for CLK2, see Table 1 for details
4	GND	PWR	Ground
5	FS0	I	Least significant bit for frequency selection, see Table 2 for details
6	FS1	I	Middle bit for frequency selection, see Table 2 for details
7	FS2	I	Most significant bit for frequency selection, see Table 2 for details
8	CLK1	O	LVC MOS output
9	O1S0	I	Least significant bit for drive strength selection for CLK1, see Table 1 for details
10	O1S1	I	Most significant bit for drive strength selection for CLK1, see Table 1 for details
11	CLK2	O	LVC MOS output
12	VDD2	PWR	Power supply for LVC MOS output CLK2, 1.65V to 3.6V ($VDD2 \leq VDD$)
13	VDD	PWR	Power supply
14	O2S1	I	Most significant bit for drive strength selection for CLK2, see Table 1 for details

Operational Description

The DSC2011FI2-F0035 is a dual output LVCMOS oscillator consisting of a MEMS resonator and a supporting PLL IC. The two LVCMOS outputs are generated through independent 8-bit programmable dividers from the output of the internal PLL. The two constraints are imposed on the output frequencies:

1) $f_2 = M \times f_1 / N$, where M and N are even integers between 4 and 254, 2) $1.2\text{GHz} < N \times f_2 < 1.7\text{GHz}$.

The actual frequencies output by DSC2011FI2-F0035 are controlled by an internal pre-programmed memory (OTP). This memory stores all coefficients required by the PLL for up to eight different frequency combinations. Three control pins (FS0 - FS2) select the output frequency combination.

DSC2011FI2-F0035 has independent control of the output voltage levels of the two outputs. The high voltage level of

CLK1 is equal to the main supply voltage, VDD (pin 13). VDD2 (pin 12) sets the high voltage level of CLK2. VDD2 must be equal to or less than VDD at all times to insure proper operation. VDD2 can be as low as 1.65V.

When OE (pin 1) is floated or connected to VDD, the DSC2011FI2-F0035 is in operational mode. Driving Enable to ground will tri-state both output drivers (hi-impedance mode).

DSC2011FI2-F0035 has programmable output drive strength for each output. Using two control pins (OXS0-OXS1) for each output, the drive strength can be independently adjusted to match circuit board impedances to reduce spower supply noise, overshoot/undershoot and EMI. Table 1 displays typical rise / fall times for the output with a 15pF load capacitance as a function of these control pins at VDD = 3.3V and room temperature.

	Output Drive Strength Bits [OXS1, OXS0] - Default is [11]			
	00	01	10	11
tr (ns)	1.6	1.4	1.2	1.1
tf (ns)	2.4	2.2	1.5	1.4

Table 1. Rise/Fall Times for Drive Strengths

Output Clock Frequencies

Frequency select bits are weakly tied high so if left unconnected the default setting will be [111] and the device will output the associated frequency highlighted in bold.

Freq (MHz)	Freq Select Bits [FS2, FS1, FS0] - Default is [111]							
	000	001	010	011	100	101	110	111
CLK1	25	NA	NA	NA	NA	NA	NA	25
CLK2	16	NA	NA	NA	NA	NA	NA	16

Table 2. Pin-Selectable Output Frequencies

Absolute Maximum Ratings

Item	Min.	Max.	Units	Condition
Supply Voltage	-0.3	+4.0	V	
Input Voltage	-0.3	VDD + 0.3	V	
Junction Temp	-	+150	°C	
Storage Temp	-55	+150	°C	
Soldering Temp	-	+260	°C	40sec max.
ESD				
HBM		4000	V	
MM		400		
CDM		1500		

1000+ years of data retention on internal memory

Specifications (Unless specified otherwise: T = 25°C, max LVC MOS drive strength)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Units
Supply Voltage ¹	VDD VDD2	VDD2 ≤ VDD	2.25 1.65		3.6 3.6	V
Supply Current	IDD	OE pin low - outputs are disabled		21	23	mA
Supply Current ²	IDD	OE pin high - outputs are enabled CL = 15pF, F01 = F02 = 125MHz		32		mA
Frequency Stability	ΔF	Includes frequency variation due to initial tolerance, temp. and power supply voltage			±25	ppm
Aging	ΔF	First year (@ 25°C)			±5	ppm
Startup Time ³	tSU	T = 25°C			5	ms
Input Logic Levels Input Logic High Input Logic Low	VIH VIL		0.75 x VDD -		- 0.25 x VDD	V
Output Disable Time ⁴	tDA				5	ns
Output Enable Time	tEN				20	ns
Pull-Up Resistor ²		Pull-up exists on all digital IO		40		kOhms
LVC MOS Outputs						
Output Logic Levels Output Logic High Output Logic Low	VOH VOL	I = ±6mA	0.9 x VDD -		- 0.1 x VDD	V
Output Transition Time ⁴ Rise Time Fall Time	tR tF	20% to 80% CL = 15pF		1.1 1.4	2 2	ns
Frequency	CLK1 CLK2	[FS2, FS1, FS0] = [1, 1, 1]		25 16		MHz
Output Duty Cycle	SYM		45		55	%
Period Jitter ⁵	JPER	F01 = F02 = 125MHz		3		psRMS
Integrated Phase Noise	JPH	200kHz to 20MHz @ 125MHz 100kHz to 20MHz @ 125MHz 12kHz to 20MHz @ 125MHz		0.3 0.38 1.7	2	psRMS

Notes:

1. Pin 12 VDD2, and pin 13 VDD should be filtered with 0.1uF capacitors.
2. Output is enabled if OE pin is floated or not connected.
3. tSU is time to 100ppm stable output frequency after VDD is applied and outputs are enabled.
4. Output Waveform and Test Circuit figures below define the parameters.
5. Period Jitter includes crosstalk from adjacent output.

Nominal Performance Parameters (Unless specified otherwise: T = 25°C, VDD = 3.3V)

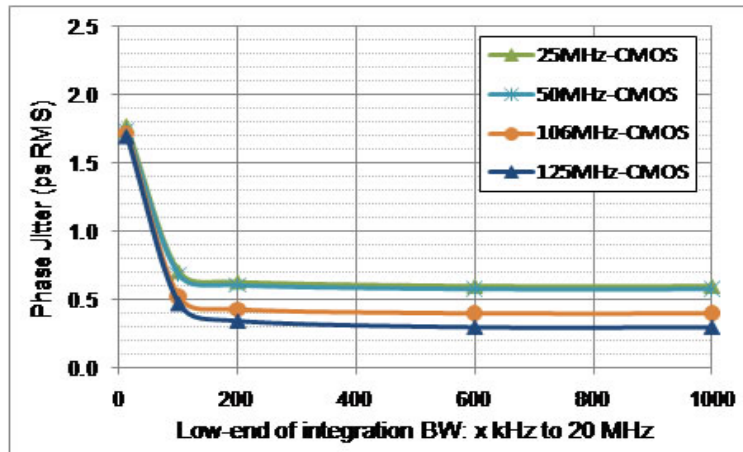


Figure 1. LVC MOS Phase Jitter (integrated phase noise)

LVC MOS Output Waveform

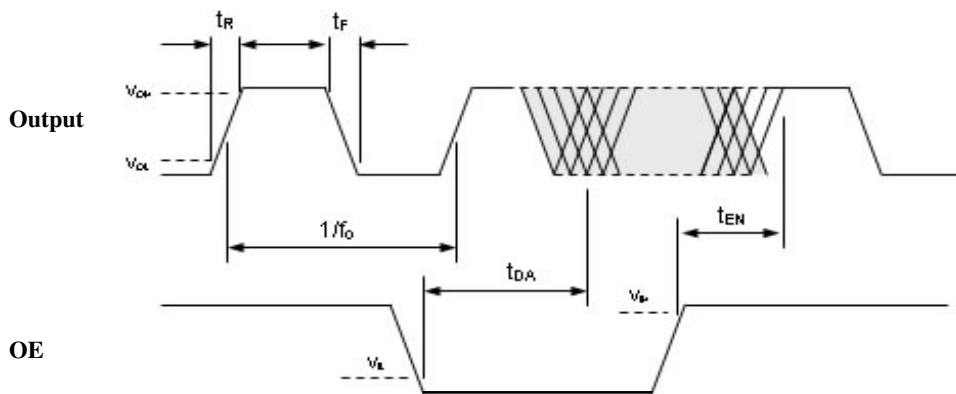


Figure 2. LVC MOS Output Waveform

MSL 1 @ 260°C refer to JSTD-020C	
Ramp-Up Rate (200°C to Peak Temp)	3°C/sec Max.
Preheat Time 150°C to 200°C	60 - 180 sec
Time maintained above 217°C	60 - 150 sec
Peak Temperature	255 - 260°C
Time within 5°C of actual Peak	20 - 40 sec
Ramp-Down Rate	6°C/sec Max.
Time 25°C to Peak Temperature	8 min Max.

Solder Reflow Profile

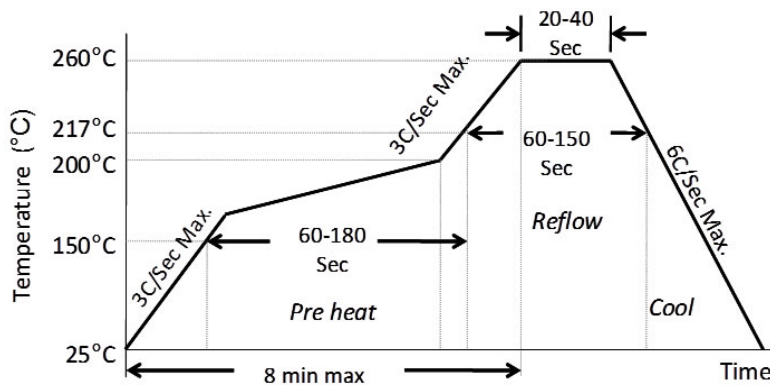
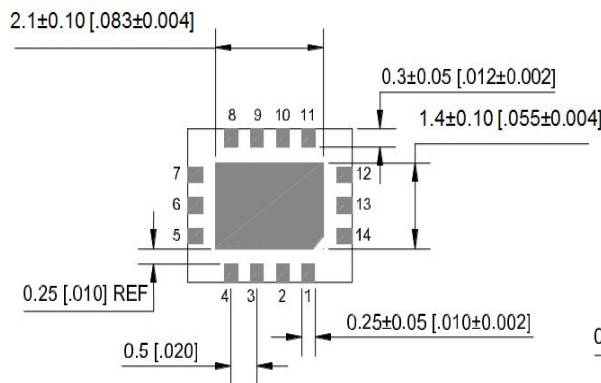
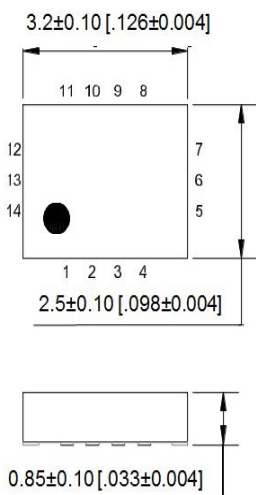


Figure 3. Solder Reflow Profile

Package Information⁷

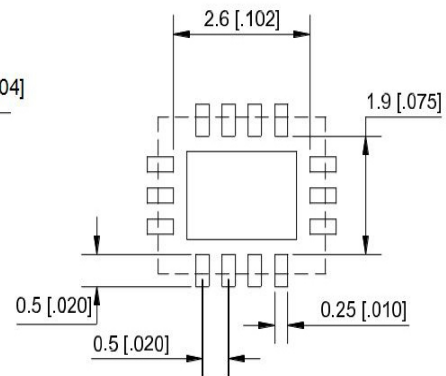
External Dimensions

units: mm[inch]



Recommended Solder Pad Layout

units: mm[inch]



3.2mm x 2.5mm 14 Lead Plastic Package

Notes:

- 6. Connect the exposed die paddle to ground.
- 7. Package information is correct as of the publication date. For updates and most current information, go to www.microchip.com.

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